

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| S1 | 2 | ("5986885").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/08 10:22 |
| S2 | 2 | ("6084295").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/08 10:25 |
| S3 | 312 | die same (mounting adj pad) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/08 10:26 |
| S4 | 985 | (die chip) same (mounting adj pad) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/08 10:26 |
| S5 | 372 | (die chip) same (mounting adj pad) same substrate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/08 10:27 |
| S6 | 6 | (("5986885") or ("6084295") or ("6620720")).PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/22 12:01 |
| S7 | 2226 | (die chip IC) same (mount\$3 with pad) same interconnect\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/22 14:02 |
| S8 | 7479 | (die chip IC) same (bond\$3 with pad) same interconnect\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/22 14:02 |
| S9 | 2123 | (die chip IC) same (bond\$3 with pad) same interconnect\$3 same (hole via) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/22 14:38 |
| S10 | 2 | ("6191477").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/22 14:38 |

| | | | | | | |
|-----|----|--|------------------------------|----|-----|------------------|
| S11 | 7 | ("5506755" "5640048" "5646826" "5721454" "5808873" "5923084" "6097089").PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2005/09/22 14:57 |
| S12 | 13 | ("3568000" "3582865" "3739469" "4535385" "4739448" "4866841" "5010641" "5102829" "5264729" "5291062" "5355283" "5397917" "5468999").PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2005/09/22 15:00 |
| S13 | 2 | ("4739448" "4855537").PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2005/09/22 15:02 |